Multilayer Ceramic Chip Capacitors



Kyocera Ceramic Chip Capacitors are available for different applications as classified below:

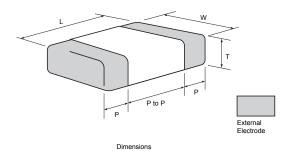
Series	Dieletric Options	Typical Applications	Features	Terminations	Available Size
СМ	C0G (NP0) X5R X7R *X6S *X7S Y5V	General Purpose	Wide Cap Range	Nickel Barrier	0201, 0402, 0603 0805, 1206, 1210 1812
CF	C0G (NP0) X7R	High Voltage & Power Circuits	High Voltage 250VDC, 630VDC 1000VDC, 2000VDC 3000VDC, 4000VDC	Nickel Barrier	0805, 1206, 1210 1812, 2208, 1808 2220
ст	COG (NPO) X5R X7R Y5V	PLCC (Decoupling)	Low Profile	Nickel Barrier	0402, 0603, 0805 1206, 1210
DM	X7R	Automotive	Thermal shock Resistivity High Reliability	Nickel Barrier	0603, 0805, 1206
CA	C0G (NP0) X5R, X7R	Digital Signal Pass line	Reduction in Placing Costs	Nickel Barrier	0405, 0508

^{*} option

Multilayer Ceramic Chip Capacitors



Dimensions



Tape & Reel

Size	EIA CODE	JIS CODE			Dimensio	ons (mm)		
Size	EIA CODE	JIS CODE	L	W	P min.	P max.	P to P min.	T max.
03	0201	0603	0.6±0.03	0.3±0.03	0.13	0.23	0.20	0.33
05	0402	1005	1.0±0.05	0.5 <u>±</u> 0.05	0.15	0.35	0.30	0.55
105	0603	1608	1.6±0.10	0.8±0.10	0.20	0.60	0.50	0.90
21	0805	2012	2.0±0.10	1.25±0.10	0.20	0.75	0.70	1.35
316	1206	3216	3.2±0.20	1.60±0.15	0.30	0.85	1.40	1.75
32	1210	3225	3.2±0.20	2.50±0.20	0.30	1.00	1.40	2.70
42	1808	4520	4.5±0.20	2.00±0.20	0.15	0.85	2.60	2.20
43	1812	4532	4.5±0.30	3.20±0.20	0.30	1.10	2.00	3.00
52	2208	5720	5.7±0.40	2.00±0.20	0.15	0.85	4.20	2.20
55	2220	5750	5.7±0.40	5.00±0.40	0.30	1.40	2.50	2.70

[•]T (Thickness) depends on capacitance value.

Standard thickness is shown on the appropriate product pages.

Bulk Cassette

Size	EIA CODE	JIS CODE		w	_	F	•	P to P
Size	SIZE LIA CODE	JIS CODE	_	VV	•	min.	max.	min.
05	0402	1005	1.0±0.05	0.5±0.05	0.5±0.05	0.15	0.35	0.30
105	0603	1608	1.6±0.07	0.8±0.07	0.8±0.07	0.20	0.60	0.50
21	0805	2012	2.0±0.1	1.25±0.1	1.25±0.1	0.20	0.75	0.70

Note) Regarding support for Bulk cases, please contact us for further information.

CA series (please refer applicable page)

[•] As for the size of the product specified individually, please contact us.

Multilayer Ceramic Chip Capacitors Ordering Information



KYOCERA PART NUMBER: CM 21 X7R 104 K 50 SERIES CODE -CM = General Purpose CA = Capacitor Arrays CF High Voltage Low Profile Automotive SIZE CODE -SIZE EIA (JIS) SIZE EIA (JIS) SIZE EIA (JIS) 03 = 0201(0603)21 = 0805 (2012)52 = 2208 (5720) 05 = 0402 (1005)316 = 1206 (3216)55 = 2220 (5750)105 = 0603 (1608)32 = 1210 (3225)D11 = 0405 (1012)/2capF12 = 0508 (1220) / 4 cap42 = 1808 (4520)D12 = 0508 (1220)/2cap43 = 1812 (4532)**DIELECTRIC CODE** -**CODE EIA CODE** X7S = X7S (Option) CG = C0G (NPO)X5R = X5RX6S = X6S (Option) X7R = X7RY5V = Y5VNegative dielectric types are available on request. CAPACITANCE CODE — Capacitance expressed in pF. 2 significant digits plus number of zeros. For Values < 10pF, Letter R denotes decimal point, 100000pF = 1041.5pF = 1R50.5pF $0.1\mu F = 104$ = R50 $100 \mu F$ 4700pF = 472= 107**TOLERANCE CODE** - $A = \pm 0.05pF$ (option) $D = \pm 0.5pF$ $J \ = \ \pm 5\%$ Z = -20 to +80% $B = \pm 0.1 pF$ (option) $F = \pm 1pF$ $K = \pm 10\%$ $C = \pm 0.25 pF$ $G = \pm 2\%$ (option) $M = \pm 20\%$ **VOLTAGE CODE** -04 = 4VDC100 = 100VDC1000 = 1000VDC06 = 6.3VDC250 = 250VDC2000 = 2000VDC10 = 10VDC400 = 400VDC3000 = 3000VDC4000 = 4000VDC16 = 16VDC630 = 630VDC25 = 25VDC35 = 35VDC50 = 50VDC**TERMINATION CODE** A = Nickel Barrier PACKAGING CODE -B = BulkL = 13" Reel Taping & 4mm Cavity pitch C = Bulk Cassette (option) H = 7" Reel Taping & 2mm Cavity pitch T = 7" Reel Taping & 4mm Cavity pitch N = 13" Reel Taping & 2mm Cavity pitch OPTION

Thickness max. value is indicated in CT series

EX. 125 \rightarrow 1.25mm max. 095 \rightarrow 0.95mm max.

Multilayer Ceramic Chip Capacitors Temperature Characteristics and Tolerance



High Dielectric Constant

EIA Dielectric	Temperature Range	∆C max.			
X5R	−55 to 85°C	⊥1 ⊑0 /			
X7R	–55 to 125°C	±15%			
*X7S	–55 to 125°C	+22%			
*X6S	–55 to 105°C	±22%			
Y5V	−30 to 85°C	-82 to +22%			

^{*} option

Temperature Compensation Type

Electric Code Value (pF)	COG	U∆ N750	SL +350 to -1000
0.5 to 2.7	CK	UK	SL
3.0 to 3.9	CJ	UJ	SL
4.0 to 9.0	СН	UJ	SL
≥10	CG	UJ	SL

K = ± 250 ppm/ °C, J = ± 120 ppm/ °C, H = ± 60 ppm/ °C, G = ± 30 ppm/ °C e.g. CG = 0 ± 30 ppm/ °C

Note: All parts will be marked as "CG" but will conform to the above table.

Available Tolerances

Dielectric materials, capacitance values and tolerances are available in the following combinations only:

EIA Dielectric	Tolerance	Capacitance
	C=±0.25pF	
	D=±0.50pF	*1 <10pF
	F=±1pF	
cog	*3 A=±0.05pF	<0.5pF
COG	B=±0.1pF	≤5pF
	*3 G=±2%	\10xF
	J=±5%	≥10pF E12 Series
	K=±10%	E12 Series
X5R X6R	*2 K=±10%	E6 Series
X7R	M=±20%	Eo Series
Y5V	Z=-20% to +80%	E3 Series

Note

E Standard Number

E3	E6	E12	E24 (C	ption)
	1.0	1.0	1.0	1.1
1.0	1.0	1.2	1.2	1.3
1.0	1.5	1.5	1.5	1.6
	1.5	1.8	1.8	2.0
	2.2	2.2	2.2	2.4
2.2	2.2	2.7	2.7	3.0
2.2	3.3	3.3	3.3	3.6
	3.3	3.9	3.9	4.3
	4.7	4.7	4.7	5.1
4.7	4.7	5.6	5.6	6.2
4.7	6.8	6.8	6.8	7.5
	0.0	8.2	8.2	9.1

^{*1} Nominal values below 10pF are available in the standard values of 0.5pF, 1.0pF, 1.5pF, 2.0pF, 3.0pF, 4.0pF, 5.0pF, 6.0pF, 7.0pF, 8.0pF, 9.0pF

^{*2} J $=\pm5\%$ for X7R (X5R) is available on request.

^{*3} optior

CM Series Nickel Barrier Terminations



[RoHS Compliant Products]

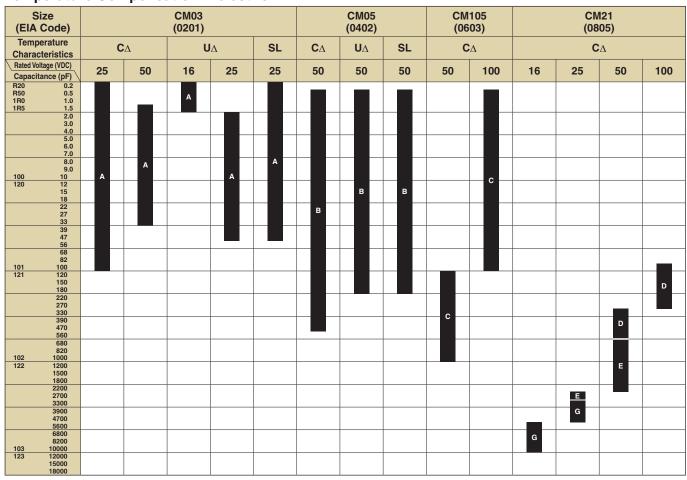
Features

We offer a diverse product line ranging from ultra–compact (0.6×0.3 mm) to large (4.3×3.2 mm) components configured for a variety of temperature characteristics, rated voltages, and packages. We offer the choice and flexibility for almost any applications.

Applications

This standard type is ideal for use in a wide range of applications, from commercial to industrial equipment.

Temperature Compensation Dielectric



Thickness and standard package quantity

			•	J .	,								
Size	*03	*05	105	*105		21, 316, 32							
Thickness	Α	В	С	С	D	Е	F	G	Н	I	J	K	L
(mm)	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	_

Size		43									
Thickness	J	K	L	M							
(mm)	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2							
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)							
Taping (330 dia reel)	_	_	_	_							

Note: P8 = 8mm width paper tape E8 = 8mm width plastic tape E12 = 12mm width plastic tape

 \ast Carrier tape 2mm pitch from one capacitor to another.

CM Series Nickel Barrier Terminations



[RoHS Compliant Products]

X5R Dielectric

	Size A Code)			CM03 (0201)					CN (04	105 02)						105 03)				CM21 (0805)				
	Voltage (VDC)	4	6.3	10	16	25	4	6.3	10	16	25	50	4	6.3	10	16	25	50	4	6.3	10	16	25	50
	citance (pF) \	7	0.0	10		23	7	0.0	10	10	23	30	7	0.0	10		23	30	7	0.0	10	10	23	30
101 151	100 150																							
151	220 330					A																		
400	470 680											В												
102 152	1000 1500 2200 3300				Α																			
103	4700 6800 10000			Α							В							С						
153	15000 22000 33000																							D E
104	47000 68000 100000									В							С	С						G
154	150000 220000 330000							В															G	
105	470000 680000 1000000								<i> </i>						С	С						G		<i> </i>
155	1500000 1500000 2200000 3300000							V///A	V///A								V///A				G	G		V////
	4700000 6800000												<i>V</i> ////	V///						G	G			
106 156	10000000 15000000																							
476	22000000																							
4/6	33000000 47000000																							

	Size CM316 (EIA Code) (1206)							CM32 (1210)						CM43 (1812)	
	Voltage (VDC) citance (pF)	6.3	10	16	25	50	4	6.3	10	16	25	50	6.3	50	
104	100000														
	220000					F						Н			
105	470000 1000000				F						Н	K			
	2200000				J						K			L	
106	4700000 10000000	J	J	J					K	-	L				
107	22000000 4700000 100000000							L ///////	L				М		

Optional Spec.

Thickness and standard package quantity

			•	•	•								
Size	*03	*05	105	*105		21, 316, 32							
Thickness	Α	В	С	С	D	Е	F	G	Н	1	J	K	L
(mm)	0.3±0.03	0.5±0.05	0.8±0.1	0.8 <u>±</u> 0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	_

Size		43							
Thickness	J	K	L	M					
(mm)	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2					
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)					
Taping (330 dia reel)	_	_	_	_					

Note: P8 = 8mm width paper tape E8 = 8mm width plastic tape E12 = 12mm width plastic tape

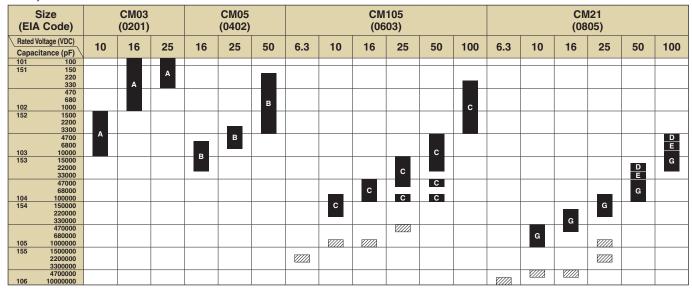
* Carrier tape 2mm pitch from one capacitor to another.

CM Series Nickel Barrier Terminations



[RoHS Compliant Products]

X7R, Dielectric



	Size (Code)		CM316 (1206)							CM32 (1210)				
	/oltage (VDC)	6.3	10	16	25	50	100	10	16	25	50	100	50	100
103	10000													
104	22000 47000 100000					Е	F					Н		
105	220000 470000 1000000			F	F	F	J			Н	H K	L	К	L
106	2200000 4700000 10000000		J					L	L	K			L	
	22000000													

Optional Spec.

Y5V Dielectric

	Size Code)	CN (02	103 01)			105 02)				105 03)			CN (08	121 05)			CM316 (1206)			CM32 (1210)	
	oltage (VDC) itance (pF)	6.3	10	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	10	16	25
102 472	1000 2200 4700		А				В														
103 473	10000 22000 47000	A			В	В	В				С										
104 474	100000 220000 470000			В					С	С			Е	E G	G G						
105 475	1000000 2200000 4700000							С				G	G	G			F	F			
106 476	10000000 22000000 47000000															J	J		К	1	1

Thickness and standard package quantity

Size	*03	*05	105	*105				2	21, 316, 3	2			
Thickness	Α	В	С	С	D	Е	F	G	Н	1	J	K	L
(mm)	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4 max.	1.6 max.	1.6±0.15	2.0±0.2	2.5±0.2
Taping (180 dia reel)	15kp (P8)	10kp (P8)	4kp (P8)	8kp (P8)	4kp (P8)	4kp (P8)	3kp (E8)	3kp (E8)	3kp (E8)	2.5kp (E8)	2.5kp (E8)	2kp (E8)	1kp (E8)
Taping (330 dia reel)	50kp (P8)	50kp (P8)	10kp (P8)	20kp (P8)	10kp (P8)	10kp (P8)	10kp (E8)	10kp (E8)	10kp (E8)	5kp (E8)	5kp (E8)	5kp (E8)	_

Size		4	3	
Thickness	J	K	L	M
(mm)	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping (180 dia reel)	1kp (E12)	1kp (E12)	0.5kp (E12)	0.5kp (E12)
Taping (330 dia reel)	_	_	_	_

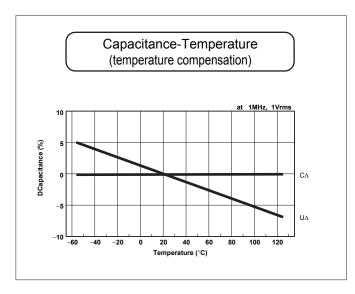
Note: P8 = 8mm width paper tape E8 = 8mm width plastic tape

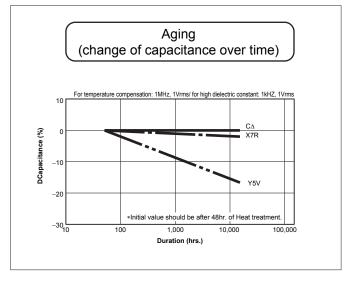
E12 = 12mm width plastic tape

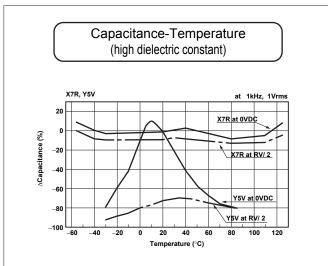
* Carrier tape 2mm pitch from one capacitor to another.

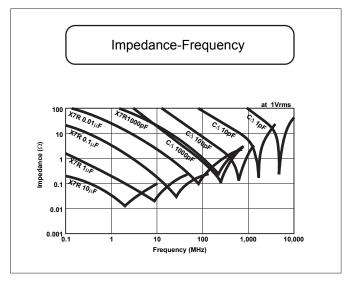
Multilayer Ceramic Chip Capacitors Electrical Characteristics

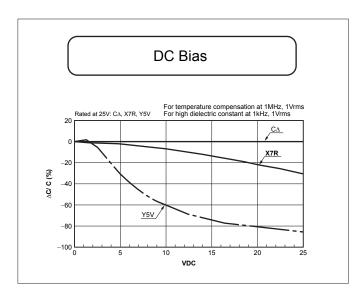


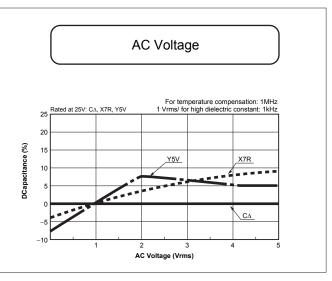












Please verify individual characteristics at the design stage to ensure total suitability.

Multilayer Ceramic Chip Capacitors Test Conditions and Standards



Test Conditions and Specifications for Temperature Compensation type (C∆ to U∆ • SL Characteristics)

Test	Items	Specifications (C: nominal capacitance)	Test Conditions				
Capacitance \	/alue	Within tolerance	C≤1000pF 1MHz±10% 0.5 to				
Q		C≥30pF: Q≥1000 C<30pF: Q≥400+20C	C>1000pF 1MHZ±10% 0.5 to 5Vrms				
Insulation res	istance (IR) (*5)	10,000M Ω or 500M Ω • μF min., whichever is less	Measured after the rated voltage is applied for one minute at normal room temperature and humidity. (*3)				
Dielectric resi	stance (*5)	No problem observed	(*1) Apply 3 times of the rated voltage for 1 to 5 second				
Appearance		No problem observed	Microscope (10×magnification)				
Termination s	trength	No problem observed	Apply a sideward force of 500g (5N) (*2) to a PCE mounted sample.				
Bending strer	ngth	No mechanical damage at 1mm bent	Glass epoxy PCB (t=1.6mm); fulcrum Spacing: 90mm; for 10 seconds.				
Vibration	Appearance	No significant change is detected	Vibration frequency: 10 to 55 (Hz)				
test ΔC Q		Within tolerance	Amplitude: 1.5mm Sweeping condition: 10→55→10Hz/ m				
		C≥30pF: Q≥1000 C<30pF: Q≥400+20C	In X, Y and Z directions: 2 hours each Total 6 hours				
Soldering Appearance heat		No significant change is detected	Soak the sample in 260°C±5°C solder for 10+0.5 seconds				
heat resistance ΔC Q IR (*5)		±2.5% or ±0.25pF max., whichever is larger	and place in a room at normal temperature				
		C≥30pF: Q≥1000 C<30pF: Q≥400+20C	and humidity; measure after 24±2 hours. (Preheating Conditions)				
		10,000MΩ or 500MΩ • μF min., whichever is smaller	Order Temperature Time 1 80 to 100°C 2 minutes				
	Withstand voltage(*5)	Resists without problem	2 150 to 200°C 2 minutes				
Solderability		Ni/ Br termination: 90% min.	Soaking Condition Sn63 Solder 235±5°C 2±0.5 sec. Sn-3Ag-0.5Cu 245±5°C 3±0.5 sec.				
Temperature	Appearance	No significant change is detected	(Cycle) Normal room temperature (3 min.) →				
cycle	ΔC	±2.5% or ±0.25pF max., whichever is larger					
	Q	C≥30pF: Q≥1000 C<30pF: Q≥400+20C	Lowest operation temperature (30 min.) → Normal room temperature (3 min.) → Highest operation temperature (30 min.) →				
	IR (*5)	10,000MΩ or 500MΩ • μF min., whichever is smaller					
	Withstand voltage(*5)	Resists without problem	After five cycles, measure after 24±2 hours				
Load	Appearance	No significant change is detected	After applied voted valtage for				
humidity test (*4)	ΔC	\pm 7.5% or \pm 0.75pF max., whichever is larger	After appling rated voltage for 500+24/ –0 hours in pre–condition at				
	Q	C≥30pF: Q≥200 C<30pF: Q≥100+10C/ 3	40±2°C, humidity 90 to 95%RH allow parts to stabilize for 48±4 hours, at room temperature before making measurements				
	IR (*5)	500MΩ or 25MΩ • μF min., whichever is smaller	temperature before making measurements				
High-	Appearance	No significant change is detected					
temperature with	ΔC	$\pm 3\%$ or ± 0.3 pF max., whichever is larger	After applying (*1) twice of the rated voltage				
loading	Q	C≥30pF: Q≥350 10pF≤C<30pF: Q≥275+5C/ 2 C<10pF: Q≥200+10C	at a temperature of 125±3°C for 1000+48/ –0 hours, measure the sample after storing 24±2 hours.				
	IR (*5)	1,000M Ω or 50M Ω • μ F min., whichever is smaller					
			*				

 $[\]ast 1$ $\,$ For the CF series, use 1.5 times when the rated voltage is 250V; use/ 1.2 times when the rated voltage exceeds 630V.

*2 2N at 0201 Size

^{*3} Apply 500V for 1 minute in case the rated voltage is 630V or higher.

^{*4} Except CF series.

^{*5} The charge and discharge current of the capacitor must not exceed 50mA.

Multilayer Ceramic Chip Capacitors Test Conditions and Standards



Test Conditions and Specifications for High Dielectric Type (X5R, X7R, Y5V)

Test	Items	Specific X7R/ X5R	cations Y5V	_	est Condition	s		
Capacitance V	/alue	Within tolerance	130	Do previous tr	eatment (*8, *14)			
Capacitance v	- and -	2.5% max., 3.5% max. (*2), 7.0% max. (*12)	5.0% max., 7.0% max. (*13)	Capacitance		Vol		
tan _δ (%)		5.0% max. (*3), 7.5% max. (*17)	9.0% max. (*4), 12.5% max. (*5)	C≤10μF C>10μF	1kHz±10% 120Hz±10%	1.0±0.2Vrms 0.5±0.2Vrms		
Insulation resi	stance (IR) (*15)	10,000M Ω or 500M Ω • μF min.,	whichever is less		rated voltage is ap nperature and humi			
Dielectric resi	stance (*15)	No problem observed		(*1) Apply 2.5 times	of the rated voltage	for 1 to 5 seconds.		
Appearance		No problem observed	Microscope (10×magnification)					
Termination s	trength (*6)	No problem observed	Apply a sideward PCB-mounted sa	force of 500g (5N) mple.	(*16) to a			
Bending stren	igth test (*6)	No problem observed at 1mm b	Glass epoxy PCB fulcrum Spacing: 90	*03, 05 type and CA	A Series: T=0.8mm);			
Vibration	Appearance	No significant change is detecte	Vibration frequency Amplitude: 1.5	ency: 10 to 55	(Hz)			
∆C		Within tolerance	Sweeping con	dition: 10→55–	→10Hz/ min.			
tanδ (%)		Satisfies the initial value	In X, Y and Z of 2 hours each					
Soldering Appearance		No significant change is detecte	Do previous tr	eatment (*8) ole in 260°C±5°	C			
heat resistance	ΔC	Within ±7.5%	solder for 10±0.5 seconds and place in a room at normal tempera					
	tanδ (%)	Satisfies the initial value		and humidity; (Preheating C	measure after 4	18±4 hours.		
	IR (*15)	10,000MΩ or 500MΩ • μF min.,	whichever is smaller	Order	Temperature	Time		
	Withstand voltage (*15)	Resists without problem		2	80 to 100°C 150 to 200°C	2 minutes 2 minutes		
		·		Soaking Condition				
Solderability		Ni/ Br termination: 90% min.		Sn63 Solder 235±5°C 2±0.5 se				
				Sn-3Ag-0.5Cu 245±5°C 3±0.5 sec. Do previous treatment (*8) (Cycle)				
Temperature cycle	Appearance	No significant change is detecte	d					
Сусіе	ΔC	Within ±7.5%	Within ±20%	Normal room temperature (3 min.) →				
	tanδ (%)	Satisfies the initial value			ion temperature emperature (3			
	IR (*15)	10,000M Ω or 500M Ω • μF min.,	whichever is smaller		tion temperatur			
	Withstand voltage (*15)	Resists without problem		After five cycle	es, measure afte	er 48±4hours.		
Load	Appearance	No significant change is detected	d	Do previous tr				
humidity test (*11)	ΔC	Within ±12.5%	Within ±30%	40±2°C and h	rated voltage a umidty 90 to 95	%RH,		
	tanδ (%)	200% max. of initial value	150% max. of initial value		hours and kee 8±4 hours then			
	IR (*15)	500M Ω or 25M Ω • μF min., whic	hever is smaller		specification lir			
High-	Appearance	No significant change is detecte	d	Do previous tr	eatment (*9)			
temperature with	ΔC	Within ±12.5%	Within ±30%	After applying	twice (*7) of the			
loading	tanδ (%)	200% max. of initial value	150% max. of initial value	voltage at the highest operating temperature for 1000+48/ –0 hours, measure the sample				
	IR (*15)	1,000MΩ or 50MΩ • μF min., wh	ichever is smaller	after storing 48±4 hours.				

- *1 Use 1.5 times when the rated voltage is 250V or over. Use 1.2 times when the rated voltage is 630V or over.
- *2 X7R 16V/ 25V type.
- *3 Apply to X5R16V/ 25V type, X7R 6.3V/ 10V type.
- *4 Apply to Y5V 16V type, CM32Y5V335 to 106 (25V Type).
- *5 Apply to Y5V 6.3V/ 10V type. Apply 16% max. to CM21Y5V106/ CM316Y5V226.
- *6 Exclude CT series with thickness of less than 0.66mm and CA series.
- *7 Use 1.5 times when the rated voltage is 4V/ 6.3V/ 10V/ 250V and 100V (32X7R474/ 43X7R105/ 55X7R105).
 - Use 1.2 times when the rated voltage is 630V or over.
- *8 Keep specimen at 150°C+0/-10°C for one hour, leave specimen at room ambient for 48±4 hours.
- *9 Apply the same test condition for one hour, then leave the specimen at room ambient for 48±4 hours.

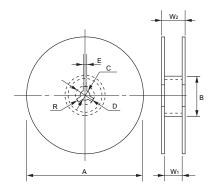
- *10 For the CF series over 630V, apply 500V for 1 minute at room ambient.
- *11 Except CF series.
- *12 Apply to X5R 10V type.
- *13 Apply to 25V series of CM105Y5V154 over, CM21Y5V105 over, 316Y5V155 over.
- *14 Measurement condition 1kHz, 1Vrms for Y5V, C<47 μ F type.
- *15 The charge/ discharge current of the capacitor must not exceed 50mA.
- 16 2N at 0201 Size
- *17 Apply to X5R 4V and 6.3V type.
- \ast The above test conditions and standards do not apply to products with optional specifications.

Multilayer Ceramic Chip Capacitors Packaging Options

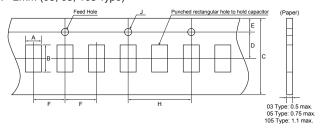


Tape and Reel

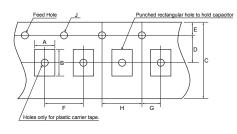
• Reel

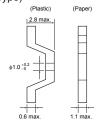


F=2mm (03, 05, 105 Type)

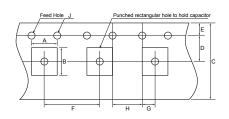


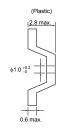
F=4mm (105, D11, D12, F12, 21, 316, 32, 42, 52 Type)





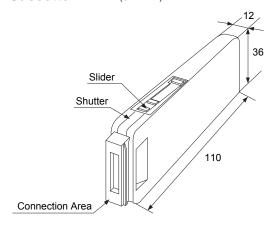
F=8mm (43, 55 Type)





Bulk Cassette

(Unit: mm)



Reel

(Unit: mm)

Code Reel	Α	В	С	D
7-inch Reel (CODE: T, H)	180 +0 -2.0	φ60 min.	13+0.5	21+0.8
13-inch Reel (CODE: L, N)	330 <u>+</u> 2.0	φ100 <u>±</u> 1.0	13 <u>±</u> 0.5	21 <u>±</u> 0.0
Code Reel	E	W 1	W ₂	R
7-inch Reel (CODE: T, H)	2.0+0.5	10.0±1.5	16.5 max.	1.0

^{*} Carrier tape width 8mm.

Carrier Tape

(Unit: mm)

•			
Туре	A	В	F
03 (0.6×0.3)	0.37±0.03	0.67±0.03	2.0±0.05
05 (1.0×0.5)	0.65±0.1	1.15±0.1	2.0±0.05
105 (1.6×0.8)	1.0±0.2	1.8±0.2	4.0±0.1
D11 (1.37×1.0)	1.15±0.2	1.55±0.2	4.0±0.1
D12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
F12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
21 (2.0×1.25)	1.5±0.2	2.3±0.2	4.0±0.1
316 (3.2×1.6)	2.0±0.2	3.6±0.2	4.0±0.1
32 (3.2×2.5)	2.9±0.2	3.6±0.2	4.0±0.1
42 (4.5×2.0)	2.4±0.2	4.9±0.2	4.0±0.1
43 (4.5×3.2)	3.6±0.2	4.9±0.2	8.0±0.1
52 (5.7×2.0)	2.4±0.2	6.0±0.2	4.0±0.1
55 (5.7×5.0)	5.3±0.2	6.0±0.2	8.0±0.1

(Unit: mm)

						,	
F	Carrier Tape	С	D	E	G	Н	J
2.0 ±0.05	8mm Paper	8.0	3.5				
4.0		±0.3	±0.05	1.75	2.0	4.0	1.5
±0.1	8mm Plastic			±0.1	±0.05	±0.1	+0.1/ -0
8.0 ±0.1	12mm Plastic	12.0 ±0.3	5.5 ±0.05				

For size 42 (1808) or over, Tape width 12mm and W1: 14 \pm 1.5, W2: 18.4mm max.

Multilayer Ceramic Chip Capacitors Precautions



Circuit Design

- 1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.
- 2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability.
 Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.
- 3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications.

 Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur. The capacitor has a loss, and may self-heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution.

 When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.
- 4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage.
 In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
 Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.
- 5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer.
 In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.
- 6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage. Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.
- 7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications.
 - In addition, it is a common piezo phenomenon of high dielectric products to have some voltage due to vibration or to have noise due to voltage change. Please contact sales in such case.
- 8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.
- 9. Please contact us upon using conductive adhesives.

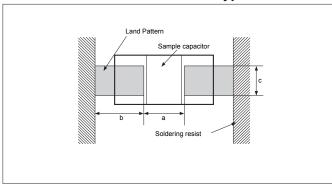
Storage

- 1. If the component is stored in minimal packaging (a heat–sealed or chuck–type plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
- 2. Keep storage place temperature +5 to +35 degree C, humidity 45 to 70% RH.
- 3. The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
- 4. Precautions 1) to 3) apply to chip capacitors packaged in carrier tapes and bulk cases.
- 5. The solderability is assured for 12 months from our shipping date (six months for silver palladium) if the above storage precautions are followed.
- 6. Chip capacitors may crack if exposed to hydrogen (H₂) gas while sealed or if coated with silicon, which generates hydrogen gas.

Multilayer Ceramic Chip Capacitors Surface Mounting Information



Dimensions for recommended typical land



When mounting the capacitor to the substrate, it is important to consider carefully that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it is mounted.

- a) The greater the amount of solder, the greater the stress to the elements. As this may cause the substrate to break or crack, it is important to establish the appropriate dimensions with regard to the amount of solder when designing the land of the substrate.
- b) In the situation where two or more devices are mounted onto a common land, separate the device into exclusive pads by using soldering resist.

Standard

(Unit: mm)

Size	L×W	а	b	С
03	0.6×0.3	0.20 to 0.30	0.25 to 0.35	0.30 to 0.40
05	1.0×0.5	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60
105	1.6×0.8	0.70 to 1.00	0.80 to 1.00	0.60 to 0.80
21	2.0×1.25	1.00 to 1.30	1.00 to 1.20	0.80 to 1.10
316	3.2×1.6	2.10 to 2.50	1.10 to 1.30	1.00 to 1.30
32	3.2×2.5	2.10 to 2.50	1.10 to 1.30	1.90 to 2.30
42	4.5×2.0	2.50 to 3.20	1.80 to 2.30	1.50 to 1.80
43	4.5×3.2	2.50 to 3.20	1.80 to 2.30	2.60 to 3.00
52	5.7×2.0	4.20 to 4.70	2.00 to 2.50	1.50 to 1.80
55	5.7×5.0	4.20 to 4.70	2.00 to 2.50	4.20 to 4.70

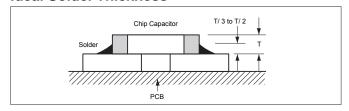
^{*} CA series: Please refer applicable page.

Automotive Series

(Unit: mm)

Size	L×W	а	b	С
105	1.6×0.8	0.60 to 0.90	0.80 to 1.00	0.70 to 1.00
21	2.0×1.25	0.90 to 1.20	0.80 to 1.20	0.90 to 1.40
316	3.2×1.6	1.40 to 1.90	1.00 to 1.30	1.30 to 1.80

Ideal Solder Thickness



Typical mounting problems

Item	Not recommended example	Recommended example/ Separated by solder
Multiple parts mount		Solder resist
Mount with leaded parts	Leaded parts	Solder resist Leaded parts
Wire soldering after mounting	Soldering iron Wire	Solder resist
Overview	Solder resist	Solder resist

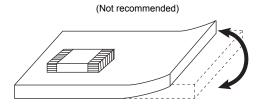
Multilayer Ceramic Chip Capacitors Surface Mounting Information

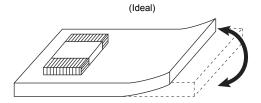


Mounting Design

The chip could crack if the PCB warps during processing after the chip has been soldered.

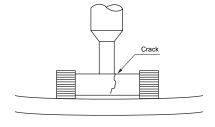
Recommended chip position on PCB to minimize stress from PCB warpage

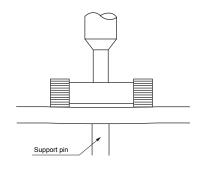




Actual Mounting

- 1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
- 2) During mounting, set the nozzle pressure to a static load of 100 to 300 gf.
- 3) To minimize the shock of the vaccum nozzle, provide a support pin on the back of the PCB to minimize PCB flexture.





- 4) Bottom position of pick up nozzle should be adjusted to the top surface of a substrate which camber is corrected.
- 5) To reduce the possibility of chipping and cracks, minimize vibration to chips stored in a bulk case.
- 6) The discharge pressure must be adjusted to the part size. Verify the pressure during setup to avoid fracturing or cracking the chips capacitors.

Resin Mold

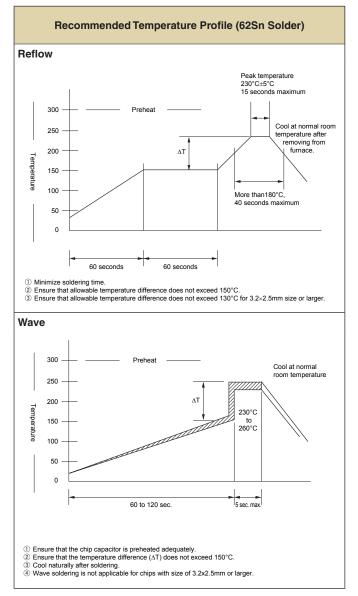
- 1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
- 2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
- 3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.

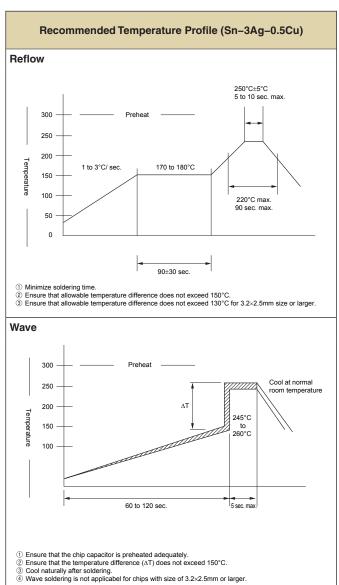
Multilayer Ceramic Chip Capacitors Surface Mounting Information



Soldering Method

- 1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 130 degree Celsius.
- 2) The product size 1.0×0.5mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of over 3.2×2.5mm, 0.6×0.3mm, and capacitor arrays can be used in reflow.
 - Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
- 3) Please see our recommended soldering conditions.
- 4) In case of using Sn-Zn Solder, please contact us in advance.





Sodering iron

1) Temperature of iron chip 380°C max. 2) Wattage 80W max. 3) Tip shape of soldering iron _{\$\psi 3.0mm max.}

3 sec. max.

4) Soldering Time

5) Cautions

a) Pre-heating is necessary Rapid heating must be avoided. Delta T≤150°C

- b) Avoid direct touching to capacitors.
- c) Avoid rapid cooling after soldering. Natural cooling is recommended.